TOSHIBA Multi-Chip Device Silicon P Channel MOS Type (U-MOS III) / Schottky Barrier Diode

# TPCF8B01

# Notebook PC Applications Portable Equipment Applications

• Low drain-source ON resistance:  $R_{DS}$  (ON) = 72 m $\dot{U}$  (typ.)

- High forward transfer admittance:  $|Y_{fs}| = 4.7 \text{ S (typ.)}$
- Low leakage current: IDSS = -10 iA (max) (VDS = -20 V)
- Enhancement-model:  $V_{th} = -0.5 \text{ to } -1.2 \text{ V}(V_{DS} = -10 \text{ V}, I_D = -200 \text{ iA})$
- Low forward voltage:  $V_{FM} = 0.46V(typ.)$

## **Maximum Ratings**

#### MOSFET (Ta = 25°C)

Cha	racteristics	Symbol	Rating	Unit		
Drain-source volta	$V_{DSS}$	-20	V			
Drain-gate voltage	Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )				٧	
Gate-source voltage	$V_{GSS}$	±8	V			
Drain current	DC	(Note 1)	I <sub>D</sub>	-2.7	Α	
	Pulse	(Note 1)	$I_{DP}$	-10.8	ζ	
Single pulse avala	Single pulse avalanche energy (Note 4)			1.2	mJ	
Avalanche current			I <sub>AR</sub>	-1.35	Α	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)			E <sub>AR</sub>	0.11	mJ	

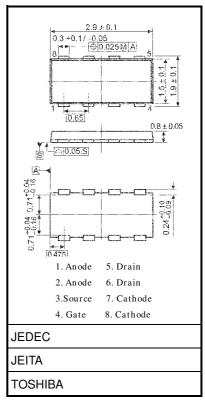
#### SBD ( $Ta = 25^{\circ}C$ )

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Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	$V_{RRM}$	20	V
Average forward current (Note 2a, 6)	I <sub>F(AV)</sub>	1.0	Α
Peak one cycle surge forward current (non-repetitive)	I <sub>FSM</sub>	7(50Hz)	Α

#### Maximum Ratings for MOSFET and SBD (Ta = 25°C)

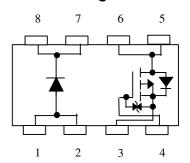
	9		•	•
Cha	Symbol	Rating	Unit	
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.35	
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	1.12	
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.53	W
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.33	
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	-55~150	°C

Unit: mm

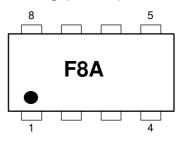


Weight: 0.011 g (typ.)

# **Circuit Configuration**



## Marking (Note 7)



Note: For (Note 1), (Note 2), (Note 3), (Note 4), (Note 5), (Note 6) and (Note 7), please refer to the next page.

#### Thermal Characteristics for MOSFET and SBD

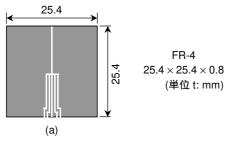
Charac	Symbol	Max	Unit		
Thermal resistance,			92.6	°C/W	
channel to ambient $(t = 5 s)$ (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	111.6	C/VV	
Thermal resistance,	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	235.8	°C/W	
channel to ambient (t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	378.8	) <b>VV</b>	

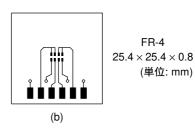
This transistor is an electrostatic sensitive device. Please handle with caution.

Schottky barrier diodes are having large-reverse-current-leakage characteristic compare to the other rectifier products. This current leakage and improper operating temperature or voltage may cause thermal runaway. Please take forward and reverse loss into consideration when you design.

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)





- Note 3: a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
  - b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).
- Note 4:  $V_{DD} = -16 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.5 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = -1.35 \text{ A}$
- Note 5: Repetitive rating; Pulse width limited by Max. Channel temperature.
- Note 6: Rectangular waveform ( $\alpha = 180^{\circ}$ ),  $V_R = 15V$ .
- Note 7: Black round marking "● " locates on the left lower side of parts number marking "F8A" indicates terminal No. 1.

# Electrical Characteristics (Ta = $25^{\circ}$ C)

# **MOSFET**

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-off curr	ent	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μΑ
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-20			V
Drain-source breakdown voltage		V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 8V$	-12	_	_	V
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -200 \mu A$	-0.5	_	-1.2	V
		R <sub>DS (ON)</sub>	$V_{GS} = -1.8 \text{ V}, I_D = -0.7 \text{ A}$	_	215	300	
Drain-source ON	resistance	R <sub>DS</sub> (ON)	$V_{GS} = -2.5 \text{ V}, I_D = -1.4A$	_	110	160	mΩ
		R <sub>DS</sub> (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -1.4 \text{ A}$	_	72	110	
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -1.4 \text{ A}$	2.4	4.7	_	S
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	470	_	pF
Reverse transfer capacitance		C <sub>rss</sub>		_	70	_	
Output capacitance		C <sub>oss</sub>		_	80	_	
	Rise time	t <sub>r</sub>	VGS -5 V	_	5	_	
Cuitobing time	Turn-on time	t <sub>on</sub>		_	9	_	
Switching time	Fall time	t <sub>f</sub>		_	8	_	ns
	Turn-off time	t <sub>off</sub>	$V_{DD} \simeq -10 \text{ V}$ Duty $\leq 1\%$ , $t_W = 10 \mu\text{s}$	_	26	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -16 \text{ V}, V_{GS} = -5 \text{ V},$	_	6	_	_
Gate-source charge		Q <sub>gs</sub>	$I_D = -2.7 \text{ A}$	_	4	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>	]	_	2	_	

**MOSFET Source-Drain Ratings and Characteristics** 

Characterist	ics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	-10.8	Α
Forward voltage (diode)		$V_{DSF}$	$I_{DR} = -2.7 \text{ A}, V_{GS} = 0 \text{ V}$		_	-1.2	V

### **SBD**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Peak forward voltage	V <sub>FM(1)</sub>	I <sub>FM</sub> = 0.7 A	_	0.43	_	V
Teak lorward voltage	V <sub>FM(2)</sub>	$I_{FM} = 1.0 \text{ A}$	_	0.46	0.49	٧
Repetitive peak reverse current	I <sub>RRM</sub>	V <sub>RRM</sub> = 20 V			50	μΑ
Junction capacitance	Cj	V <sub>R</sub> = 10 V, f = 1 MHz		54		pF

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